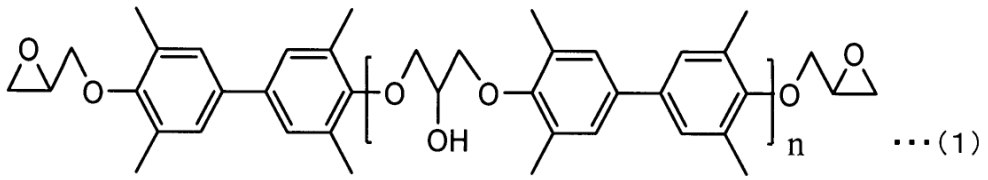
CLAIMS

1. An epoxy resin represented by the following formula (1), having a number average molecular weight (Mn) of 270 to 300, an epoxy equivalent of 199 to 275 g/eq, and a content of hydrolyzable chlorine of 90 ppm or less relative to the epoxy resin,

[Chem. 2]



wherein in the formula, n represents an integer of 0 to 10.

2. An epoxy resin composition comprising from 0.1 to 1,000 parts by weight of a curing agent per 100 parts by weight of the epoxy resin according to claim 1.

3. The epoxy resin composition according to claim 2, wherein the curing agent is at least one curing agent selected from the group consisting of a phenolic curing agent, an amine curing agent, an acid anhydride curing agent, and an amide curing agent.

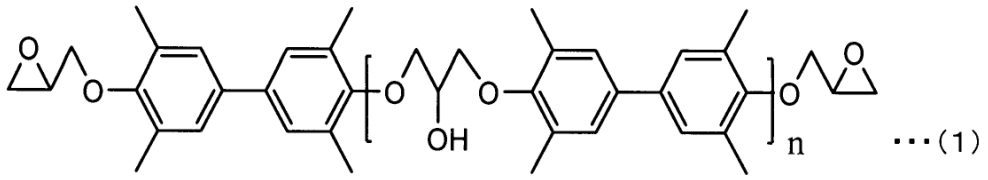
4. The epoxy resin composition according to claim 2 or claim 3, further comprising an epoxy resin different from the epoxy resin according to claim 1.

5. A cured product obtained by curing the epoxy resin composition according to any one of claims 2 to 4.

6. An electric or electronic component obtained by curing the epoxy resin composition according to any one of claims 2 to 4.

7. An epoxy resin represented by the following formula (1), having a weight average molecular weight (Mw) or 370 to 610, an epoxy equivalent of 199 to 275 g/eq, and a content of hydrolyzable chlorine of 90 ppm or less relative to the epoxy resin,

[Chem. 3]



wherein in the formula, n represents an integer of 0 to 10.

8. An epoxy resin composition comprising from 0.1 to 1,000 parts by weight of a curing agent per 100 parts by weight of the epoxy resin according to claim 7.

9. The epoxy resin composition according to claim 8, wherein the curing agent is at least one curing agent selected from the group consisting of a phenolic curing agent, an amine curing agent, an acid anhydride curing agent, and an amide curing agent.

10. The epoxy resin composition according to claim 8 or claim 9, further comprising an epoxy resin different from the epoxy resin according to claim 7.

11. A cured product obtained by curing the epoxy resin composition according to any one of claims 8 to 10.

12. An electric or electronic component obtained by curing the epoxy resin composition according to any one of claims 8 to 10.